HX Types

H A 1 - 5134 A -2 Z 96

PREFIX

FAMILY
A: Analog
C: Communications
D: Digital
I: Interface
M: Memory
V: Analog High Voltage

PACKAGE DESIGNATOR
1: Ceramic Dual-In-Line Frit-Seal (CERDIP)
1B: Ceramic Dual-In-Line Metal-Seal (SBDIP)
2: Can
3: Dual-In-Line Plastic (PDIP)
4: Ceramic Leadless Chip Carriers (CLCC)
4P: Plastic Leaded Chip Carrier (PLCC)
6: Narrow Dual-In-Line Plastic (PDIP) or Ceramic Dual-In-Line Frit-Seal (CERDIP)
7: 8 Lead Ceramic Dual-In-Line Frit-Seal (CERDIP)
9P: Small Outline Plastic (SOIC)
0: Chip

NOTE: If the package designator is 2 characters the hyphen is omitted from the part number.

PART NUMBER

PERFORMANCE GRADE
A, B: High Performance
C: Relaxed Specification
S: Very High Speed

NOTE: Applies to HA, HD and HM products only.

TEMPERATURE RANGE
-2: -55°C to +125°C
-4: -25°C to +85°C
-5: 0°C to +75°C
-6: +25°C Chip Probe
-7: Dash-7 High Reliability Commercial Product 0°C to +75°C, Includes 96 hour Burn-In
-8: -55°C to +125°C Intersil Class B Equivalent Devices for use in Military and Flight Systems
-9: -40°C to +85°C
/883: Fully Compliant to MIL-STD-883, Class B/QML
BXXXX: Customer Specific Screening
RXXXX: Customer Specific Screening
SXXXX: Customer Specific Screening

SUFFIX
96: Tape and Reel Option for SOIC, PLCC
X96: Tape and Reel Option for SOIC, PLCC
EVAL: Evaluation Platform

PB-FREE OPTION
Z: Pb-Free Product
ZA: Pb-Free with Anneal

HX, HXX Types

H A 4314B C B Z 96

PREFIX

FAMILY
A: Analog
C: Communications
FA: Ultra-High Frequency Analog
I: Data Acquisition, DSP Function-Specific
V: Analog High Voltage

PART NUMBER

TEMPERATURE RANGE
C: 0°C to +70°C
I: -40°C to +85°C
M: -55°C to +125°C

PACKAGE DESIGNATOR
A: Shrink Small Outline Plastic (SSOP)
B: Small Outline Plastic (SOIC)
D: Ceramic Dual-In-Line Metal-Seal (SBDIP)
H: Plastic Small Outline Transistor (SOT)
J: Ceramic Dual-In-Line Frit-Seal (CERDIP)
L: Ceramic Leadless Chip Carrier (CLCC)
M: Plastic Leaded Chip Carrier (PLCC)
N: Thin Quad Flatpack (TQFP), or Metric Quad Flatpack (MQFP)
Q: Metric Plastic Quad Flatpack (MQFP), or Plastic Quad Flatpack (PQFP)
P: Dual-In-Line Plastic (PDIP)
T: Can
Y: Chip (Commercial Visual)
W: Wafer

SUFFIX
/883: Fully Compliant to MIL-STD-883 Class B/QML
96: Tape and Reel
-T: Tape and Reel
EVAL: Evaluation Platforms

PB-FREE OPTION
Z: Pb-Free Product
ZA: Pb-Free with Anneal

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